

SPECIFICATION SHEET

SPECIFICATION SHEET NO.	Q0526- CR0201JM300KS1
DATE	May. 26, 2023
REVISION	A0
DESCRIPITION	Thick Film Chip Resistors, 0201 (0603 Metric), CR01 Series, Dimension L0.60*W0.30*H0.23mm, 2 Terminations Tolerance: ±5%, Resistance 300K ohm, Dissipation Max. 1/20W @ 70°C Temperature Coefficient Rate (TCR) Max. ±200ppm/°C Operating Temp. Range -55°C ~+125°C Package in Tape/Reel, 15,000pcs/Reel RoHS/RoHS III compliant and HF
CUSTOMER	
CUSTOMER PART NUMBER	
CROSS REF. PART NUMBER	
ORIGINAL PART NUMBER	Aillen CR01JM300K
PART CODE	CR0201JM300KS1

VENDOR APPROVE Issued/Checked/Approved

CUSTOMER APPROVE
DATE:
5/26/2023



THICK FILM CHIP RESISTORS CR01 SERIES

DESCRIPTION

The resistors are constructed in a high grade ceramic body (aluminum oxide). Internal metal electrodes are added at each end and connected by a resistive paste that is applied to the top surface of the substrate. The composition of the paste is adjusted to give the approximate resistance required and the value is trimmed to within tolerance by laser cutting of this resistive layer. The resistive layer is covered with a protective coat. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Tin (lead free) alloy.

MAIN FEATURE

- High Reliability And Stability
- Reduced Size Of Final Equipment
- Lower Assembly Costs
- Higher Component And Equipment Reliability
- RoHS III Compliant And Halogen Free Products

APPLICATION

- Consumer Electrical Equipment
- EDP, Computer Application
- Telecom Application

PART CODE GUIDE

CR	0201	J	М	300К	S1
1	2	3	4	5	6

1) CR: Product code for Thick Film Chip Resistors

2) 0201: Size Code, 0201 (0603 Metric), CR01 Series, Dimensions L0.60*W0.30*H0.23mm,

3) J: Resistance Range Tolerance Code, P: Jumper; B: +/-0.1%; D: +/-0.5%; F: +/-1%; J: +/-5%

4) M: Package Code, A: 4Kpcs/7"Reel; B:5kpcs/7"Reel; C:10kpcs/7"Reel; M:15kpcs/7"Reel; D:10kpcs/10"Reel; E:20kpcs/10"Reel

5) 300K: Resistance value code. 0R: 0ohm; 1R2: 1.2ohm; 10R: 10ohm; 20R: 20ohm; 51R: 51ohm; 120R: 120ohm; 240R: 240ohm

1K: 1Kohm; 3K: 3Kohm; 8K2: 8.2Kohm; 10K: 10 Kohm; 20K: 20Kohm; 100K: 100Kohm; 300K: 300Kohm; 1M: 1.0Mohm; 3M:

3.0Mohm

6) S1: Internal control code, digits and letter; Blank: N/A

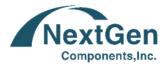
5/26/2023

NextGen Components, Inc.

2







THICK FILM CHIP RESISTORS CR01 SERIES

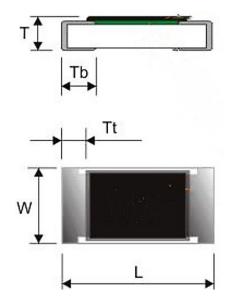
DIMENSION (Unit: mm)

Image for reference



General Marking: Blank

CR01 series



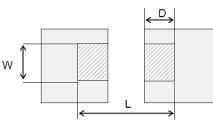
Item	Dimension
L	0.60±0.03
w	0.30±0.03
Т	0.23±0.03
Тb	0.15±0.05
Tt	0.10±0.05



Recommended Solder Pad

Resistors Construction

For Reference



ltem	Dimension (mm)
w	0.25~0.30
L	0.70~0.90
D	0.30~0.40

5/26/2023

NextGen Components, Inc.

3



THICK FILM CHIP RESISTORS CR01 SERIES

GENERAL ELECTRONICAL CHARACTERISTICS

	Item	Unit	Symbol	Characteristic	Condition
Product Name			CR	Thick Film Chip Resistors	
Size			0201	CR01 Series, L0.60*W0.30*H0.23mm	
Resist	tance Range	Ω		300К	
Resista	nce Tolerance	%	J	+/-5	
TCR	10Ω~10ΜΩ	ppm/°C		≤±200	
	1Ω~9.76Ω			-200~+600	-
Max.	Dissipation	W		1/20	@ Tamb=70°C
Operatin	g Temperature	°C		-55 ~+125	
Max. Ope	eration Voltage	V		25	@DC or RMS
Max. Ov	erload Voltage	V		50	@DC or RMS

Note

1) This is the maximum voltage that may be continuously supplied to the resistor element, see "IEC publication 60115-8"

2) Max. Operation Voltage : So called RCWV (Rated Continuous Working Voltage) is determined by

RCWV = $\sqrt{Rated Power \times Resistance Value}$ or Max. RCWV listed above, whichever is lower.

3) Test condition for jumper (0 Ω)

Item	Unit	Symbol	Characteristic	Condition
Power Rating At 70°C	W		1/20	
Max. Resistance	mΩ		50	
Rated Current	А		1.0	
Peak Current	А		2.5	
Operating Temperature	°C		-55 ~+125	

5/26/2023



THICK FILM CHIP RESISTORS CR01 SERIES

PRODUCT CHARACTERIZATION

Standard values of nominal resistance are taken from the E24 & E96 series for resistors with a tolerance Of +/-1% &

+/-5%, The values of the E24/E96 series are in accordance with "IEC publication 60063"

DERATING

The power that the resistor can dissipate depends on the operating temperature; see Fig.1

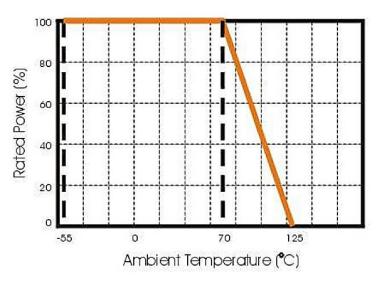


Fig 1 Maximum dissipation in percentage of rated power as a function of the ambient temperature for CR0402

MOUNTING

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems. Chip placement can be on ceramic substrates and printed-circuit boards (PCBs). Electrical connection to the circuit is by individual soldering condition. The end terminations guarantee a reliable contact.

5/26/2023

NextGen Components, Inc.



THICK FILM CHIP RESISTORS CR01 SERIES

REFLOW SOLDERING CONDITION

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260 $^{\circ}$ C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs). Surface Mount Resistors are tested for solderability at 235 $^{\circ}$ C during 2 seconds. The test condition for no leaching is 260 $^{\circ}$ C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2.

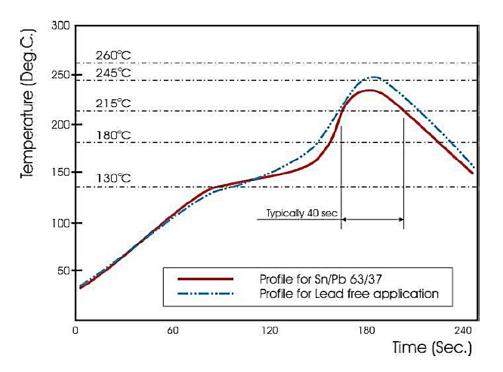


Fig 2. Infrared soldering profile for Chip Resistors



THICK FILM CHIP RESISTORS CR01 SERIES

TEST AND REQUIREMENT (JIS C 5201-1: 1998)

TEST	PROCEDURE / TEST METHOD	REQUIREMENT		
		Resistor	0Ω	
Electrical	- DC resistance values measurement	Within the	<50mΩ	
Characteristics	- Temperature Coefficient of Resistance (T.C.R)	specified tolerance		
JISC5201-1: 1998	Natural resistance change per change in degree	Refer to "QUICK		
Clause 4.8	centigrade. $\frac{R_2-R_1}{R_1(t_2-t_1)}{\times}10^6~{\rm (ppm/^{o}C)}$	REFERENCE DATA"		
	t1 : 20°C+5°C-1°C; t2 : -55°C or +125°C			
	R1 : Resistance at reference temperature			
	(20°C+5°C/- 1°C)			
	R2: Resistance at test temperature (-55°C or +125°C)			
Short time overload (S.T.O.L) Clause 4.13	Permanent resistance change after a 5second application of a voltage 2.5 times RCWV or the maximum overload voltage specified in the above list,	ΔR/R max. ±(2%+0.10Ω)	<50mΩ	
	whichever is less.			
Resistance to	Un-mounted chips completely immersed for	ΔR/R max.	<50mΩ	
soldering heat(R.S.H)	10±1second in a SAC solder bath at 260℃±5℃	± (1%+0.05Ω)		
Clause 4.18		no visible damage		
Solderability	Un-mounted chips completely immersed for 2±0.8	95% coverage min., g	ood	
Clause 4.17	second in a SAC solder bath at $235^{\circ}C\pm 5^{\circ}C$	tinning and no visible	damage	
Temperature cycling Clause 4.19	30 minutes at -55°C±3°C, 2~3 minutes at 20°C+5°C- 1°C, 30 minutes at +125°C±3°C, 2~3 minutes at 20°C+5°C1°C, total 5 continuous cycles	ΔR/R max. ±(1%+0.05Ω)	<50mΩ	
Damp Heat	1000 +48/-0 hours, loaded with RCWV or Vmax in	10Ω≤R<1MΩ :	<50mΩ	
(Load life in	humidity chamber controller at 40°C±2°C and	ΔR/R max.		
humidity)	90~95% relative humidity, 1.5hours on and 0.5 hours	±(3%+0.10Ω)		
Clause 4.24	off	R<10Ω, R≥1MΩ :		
		ΔR/R max. ±(5%+0.10Ω)		

5/26/2023

NextGen Components, Inc.



THICK FILM CHIP RESISTORS CR01 SERIES

TEST AND REQUIREMENT (JIS C 5201-1: 1998)

TEST	PROCEDURE / TEST METHOD	REQUIREMENT		
		Resistor	0Ω	
Load Life (Endurance)	1000+48/-0 hours; loaded with RCWV or V max in	Ditto.		
Clause 4.25	chamber controller 70±2°C, 1.5 hours on and 0.5			
	hours off			
Bending strength	Resistors mounted on a 90mm glass epoxy resin	No visual damaged,	<50mΩ	
Clause 4.33	PCB(FR4), bending once 5mm for 10sec	ΔR/R max. ±(1%+		
		0.05Ω)		
Adhesion	Pressurizing force: 3N, Test time: 10±1sec.	No remarkable damage or		
Clause 4.32		removal of the terminations		

STORAGE AND HANDLING CONDITIONS

1) Products are recommended to be used up within two years since operation date as ensured shelf life. Check solderability in case shelf life extension is needed.

2) To store products with following condition: Temperature : 5 to 40°C Humidity: 20 to 70% relative humidity

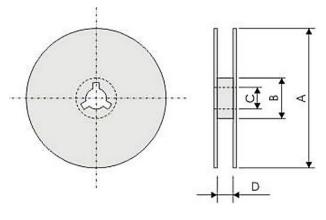
3) Don't store products in a corrosive environment such as sulfide, chloride gas, or acid. It may cause oxidization of electrode, which easily be resulted in poor soldering b.To store products on the shelf and avoid exposure to moisture. Don't expose products to excessive shock, vibration, direct sunlight and so on.



THICK FILM CHIP RESISTORS CR01 SERIES

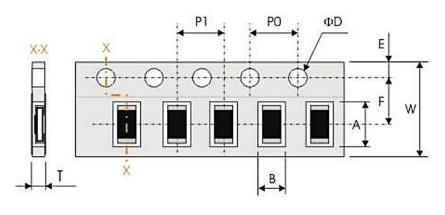
REEL DIMENSION (Unit: mm)

7": 15,000Ppcs/Reel



Code	Dimension 7"	Dimension 10"	Dimension 13"	
Α	178.0+/-2.0	254.0+/-2.0	330.0+/-2.0	
В	60.0 +/-1.0	100 +/-1.0	100+/-1.0	
С	13.0+/-0.20	13.0+/-0.20	13.0+/-0.20	
Т	9.0+/-0.50	9.0+/-0.5	9.0+/-0.5	

TAPE DIMENSION (Unit: mm)



Code	Dimension		
А	0.67±0.05		
В	0.37±0.05		
W	8.00±0.20		
F	3.50±0.05		
E	1.75±0.10		
P 1	2.00±0.05		
PO	4.00±0.05		
ΦD	1.50±0.10		
Т	0.45±0.05		

TAPING QUANTITY AND TAPE MATERIAL

Таре	Paper Tape						Embossed Tape	Bulk Cassette
		4 mm Pitch	2 mm Pitch			4 mm Pitch		
Reel Size	7"	10"	13″	7"	10"	13″	7"	
CR01	-	-	-	15000pcs	-	-	-	-



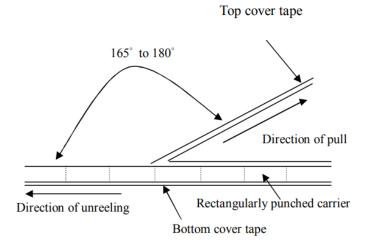
THICK FILM CHIP RESISTORS CR01 SERIES

PERFORMANCE OF TAPING

Strength of Carrier Tape and Top Cover Tape

Carrier Tape: When a tensile force 1.02kgf is applied in the direction of unreeling the tape, the tape shall withstand this force. Top cover Tape: When a tensile force 1.02kgf is applied to the tape, the tape shall withstand this force. Peel Force of Top Cover Tape

Unless otherwise specified, the peel force of top cover tape shall be 10.2 to 71.4 g f when the top cover tape is pulled at a speed of 300mm/min with the angle between the taped during peel and the direction of unreeling maintained at 165 to 180°as illustrated in Fig.



DISCLAIMER

NextGen Component, Inc. reserves the right to make changes to the product(s) and or information contained herein without notice. No liability is assumed as a result of their use or application. No rights under any patent accompany the sale of any such product(s) or information

5/26/2023

NextGen Components, Inc.